

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







Product Data Sheet



| t-Global Part No. | LP0001/01-Li2000A-0.2 | | | | | |
|--|--|----------------------|---|---------------------------|--|----------|
| Digi-Key Part No. | 1168-1716-ND | | | | | |
| Description | Thermal tape | | | | | |
| Manufacturer t | t-Global Technology | | | | | |
| Part Number scheme | [LP][PCB type]/[##]-[XXX]-[T]-[#A]-[P] | | | | | |
| | [LP][PCB type]/ | ## | XXX | T | #A | Р |
| | Die-Cut for PCB type: LP0001 | Variant: 01 | T-Global thermal interface pad material: Li2000A | Thickness 0.2mm | Adhesive 1A – one side 2A –two sides | Pull tab |
| Typical application | Thermal interface pa | d for LED Star board | d | | | |
| Material code | Li2000A | Unit | Thermal pad dimensions (mm) | | | |
| Thickness | 0.25 | mm | R0.80 x 12 9.5 R1.6 x 6 Equally Spaced on 19.0mm. Pitch Circle Dia. as shown | | | |
| Reinforcement carrier | - | - | | | | |
| Features | Good adhesion High thermal conductivity High bond strength Long-term temperature stability Good insulation | | | | | |
| Holding power 1Kg @ 25 °C Using 1 in ² | › 40000 | min | | | | |
| Thermal conductivity | 2 | W/m.K | | | | |
| Thermal impedance @ < 1psi | 0.7 | °C/W | | | | |
| Lap shear strength | 35 | N/cm² | | | | |
| Die shear strength @ 25 °C | 60 | N/cm² | | | | |
| Operating temperature range | -45 to 170 | °C | | | | |
| Dielectric breakdown voltage(Vac) | › 3.5 | kV | | | | |
| Flame rating | V-0 | UL94 |] | | | |
| | White | | | | | |
| Colour | | | | | | |
| | | | | | | |

Revision of these specifications is carried out after consent. We reserve the right to make changes without notification.